

AOL1414
N-Channel Enhancement Mode Field Effect Transistor
General Description

The AOL1414 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and low gate resistance. This device is ideally suited for use as a high side switch in CPU core power conversion.

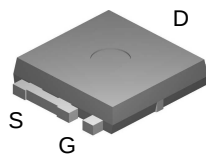
- RoHS Compliant
- Halogen and Antimony Free Green Device*

Features

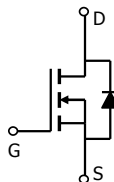
V_{DS} (V) = 30V
 I_D = 85A (V_{GS} = 10V)
 $R_{DS(ON)} < 6.5m\Omega$ (V_{GS} = 10V)
 $R_{DS(ON)} < 7.5m\Omega$ (V_{GS} = 4.5V)

UIS Tested
 $R_g, C_{iss}, C_{oss}, C_{rss}$ Tested

Ultra SO-8™ Top View



Bottom tab
connected to
drain


Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^B	I_D	85	A
$T_C=25^\circ\text{C}$			
$T_C=100^\circ\text{C}$		70	
Pulsed Drain Current	I_{DM}	200	
Continuous Drain Current ^G	I_{DSM}	14	
$T_A=25^\circ\text{C}$			
$T_A=70^\circ\text{C}$		11	
Avalanche Current ^C	I_{AR}	30	A
Repetitive avalanche energy $L=0.3mH$ ^C	E_{AR}	135	mJ
Power Dissipation ^B	P_D	100	W
$T_C=25^\circ\text{C}$			
$T_C=100^\circ\text{C}$		50	
Power Dissipation ^A	P_{DSM}	2.08	W
$T_A=25^\circ\text{C}$			
$T_A=70^\circ\text{C}$		1.3	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	14.4	25	$^\circ\text{C/W}$
$t \leq 10s$				
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	37	60	$^\circ\text{C/W}$
Steady-State				
Maximum Junction-to-Case ^C	$R_{\theta JC}$	1	1.5	$^\circ\text{C/W}$
Steady-State				

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1	1.5	2	V
$I_{D(ON)}$	On state drain current	$V_{GS}=10\text{V}$, $V_{DS}=5\text{V}$	100			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=20\text{A}$ $T_J=125^\circ\text{C}$		4.9 6.9	6.5 8.3	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=20\text{A}$		6	7.5	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=20\text{A}$		90		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$, $V_{GS}=0\text{V}$		0.74	1	V
I_S	Maximum Body-Diode Continuous Current				85	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=15\text{V}$, $f=1\text{MHz}$		2100	2520	pF
C_{oss}	Output Capacitance			536		pF
C_{rss}	Reverse Transfer Capacitance			165	231	pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$	0.5	0.95	1.5	Ω
SWITCHING PARAMETERS						
$Q_g(4.5\text{V})$	Total Gate Charge	$V_{GS}=4.5\text{V}$, $V_{DS}=15\text{V}$, $I_D=20\text{A}$		19.7	24	nC
Q_{gs}	Gate Source Charge			3.6	4.6	nC
Q_{gd}	Gate Drain Charge			7.9		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=10\text{V}$, $V_{DS}=15\text{V}$, $R_L=0.75\Omega$, $R_{GEN}=3\Omega$		5.9	10	ns
t_r	Turn-On Rise Time			11	17	ns
$t_{D(off)}$	Turn-Off DelayTime			36.2	55	ns
t_f	Turn-Off Fall Time			12	18	ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		35	42	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		33	50	nC

A: The value of $R_{\theta JA}$ is measured with the device in a still air environment with $T_A=25^\circ\text{C}$.

B: The power dissipation P_D is based on $T_{J(MAX)}=175^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=175^\circ\text{C}$.

D: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.

E: The static characteristics in Figures 1 to 6 are obtained using $<300\mu\text{s}$ pulses, duty cycle 0.5% max.

F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}=175^\circ\text{C}$.

G: The maximum current rating is limited by bond-wires.

H: These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

* This device is guaranteed green after date code 8P11 (June 1ST 2008)

Rev 5: May 2010

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

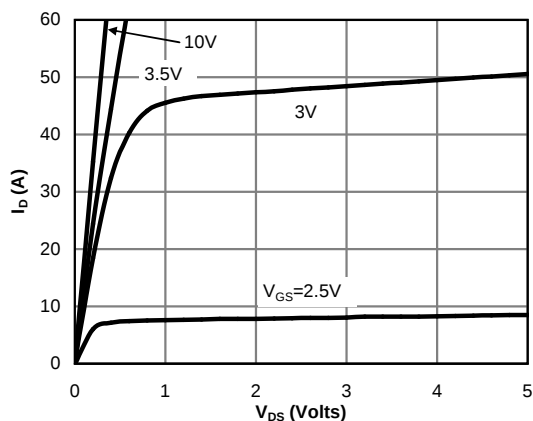


Fig 1: On-Region Characteristics

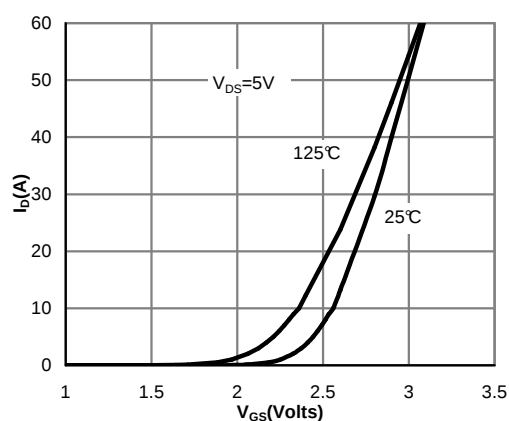


Figure 2: Transfer Characteristics

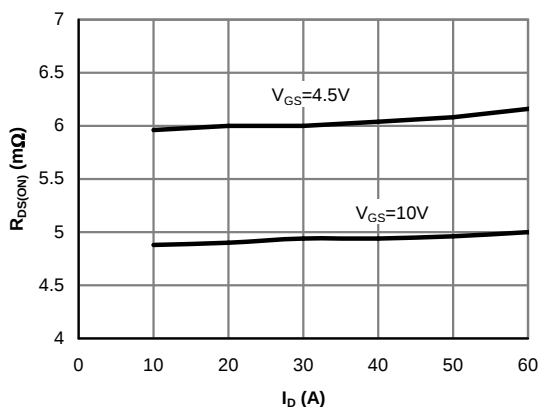


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

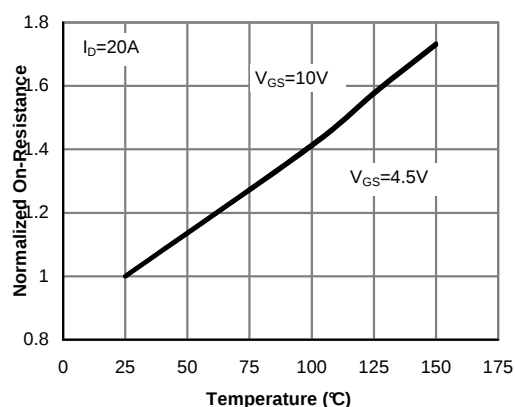


Figure 4: On-Resistance vs. Junction Temperature

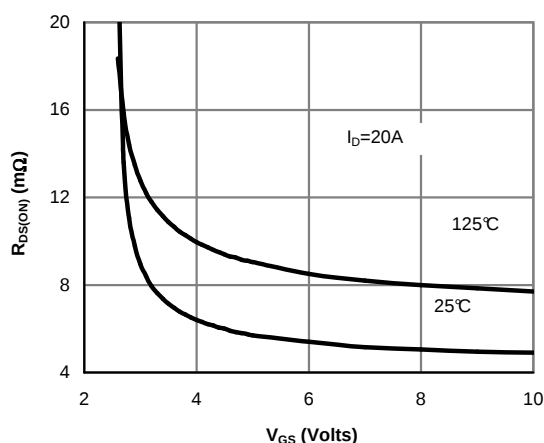


Figure 5: On-Resistance vs. Gate-Source Voltage

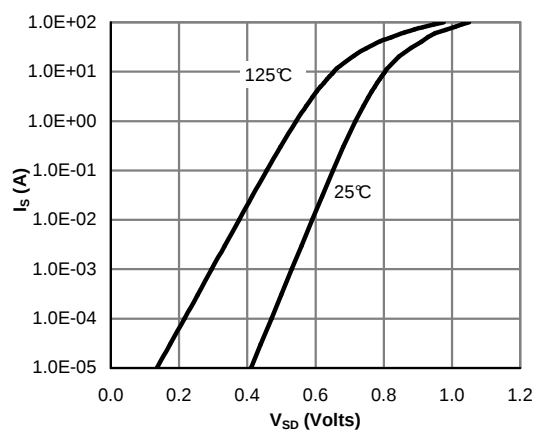


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

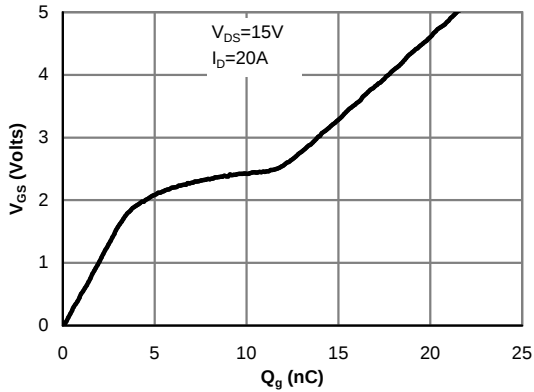


Figure 7: Gate-Charge Characteristics

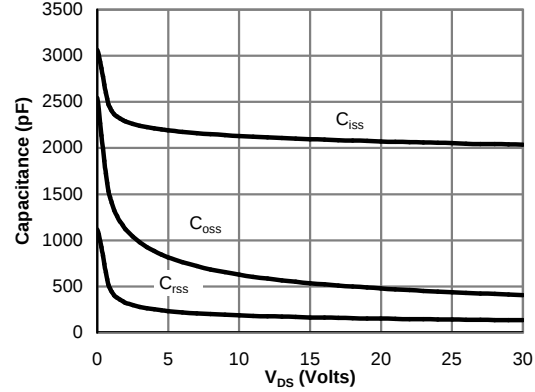


Figure 8: Capacitance Characteristics

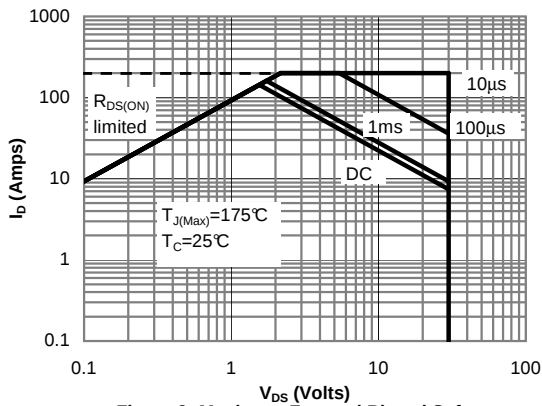


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

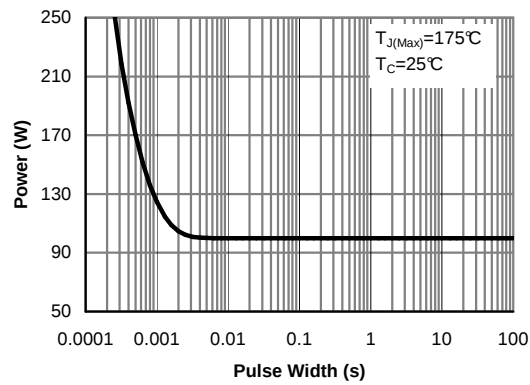


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

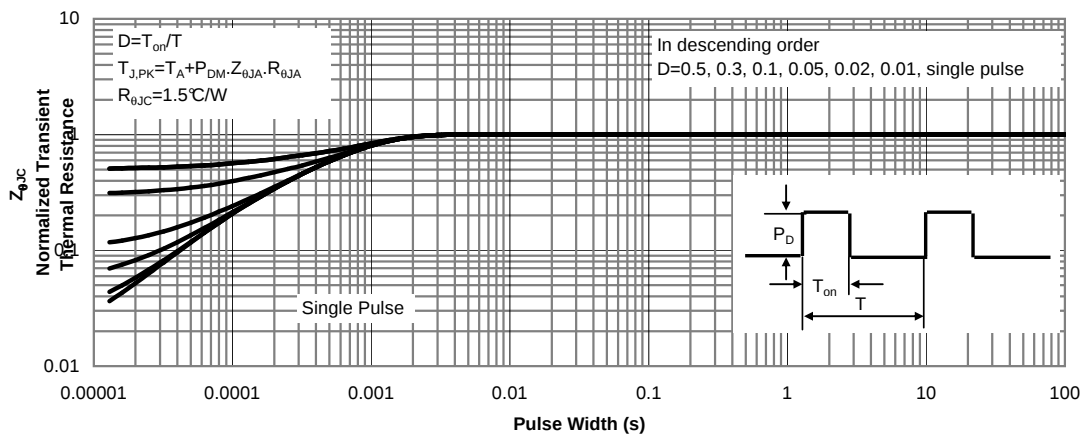


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

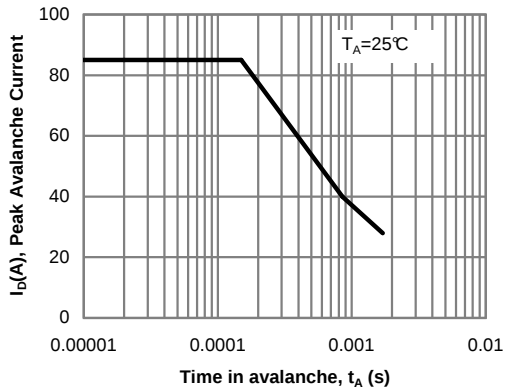


Figure 12: Single Pulse Avalanche capability

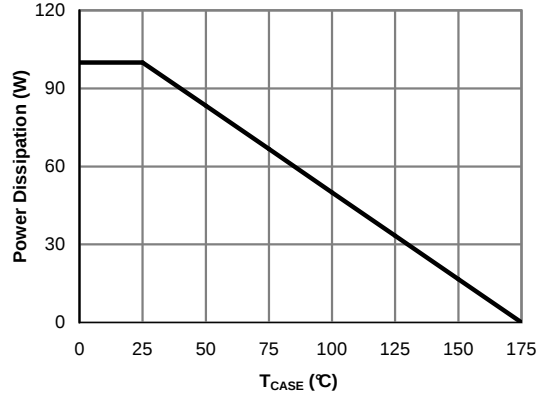


Figure 13: Power De-rating (Note B)

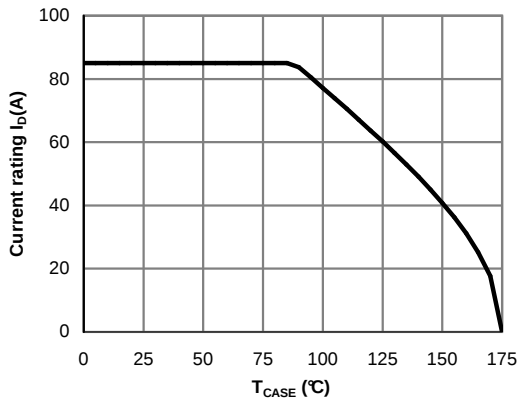


Figure 14: Current De-rating (Note B)

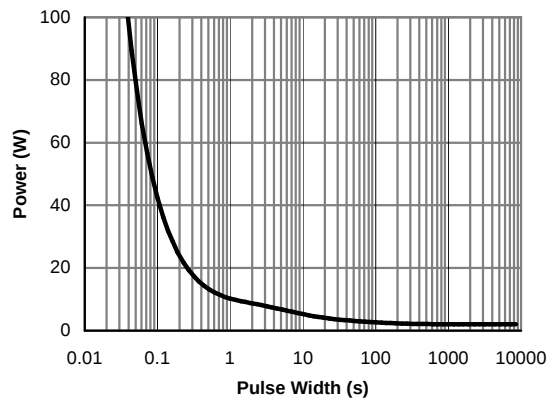


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

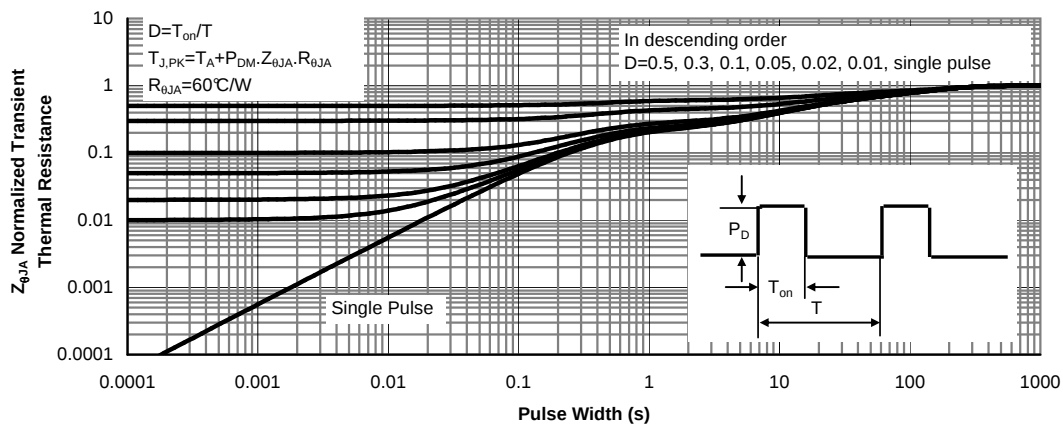
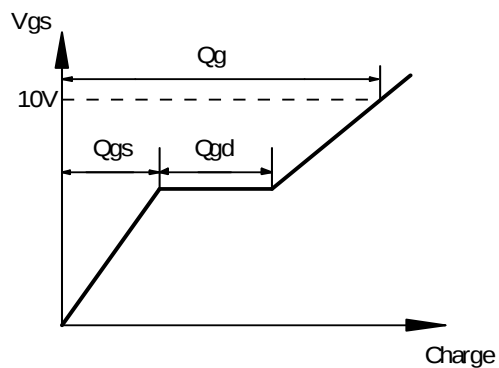
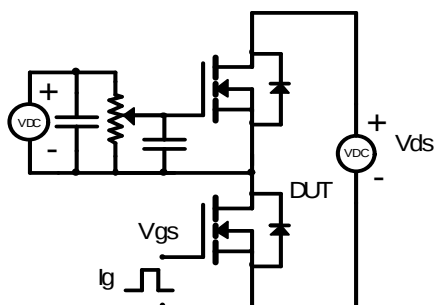
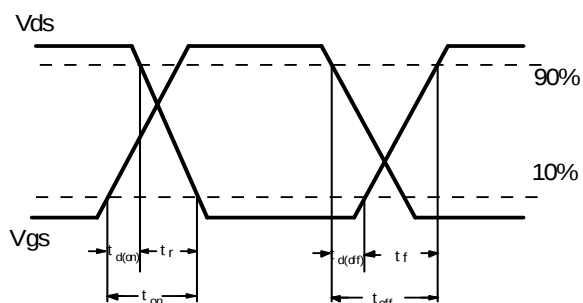
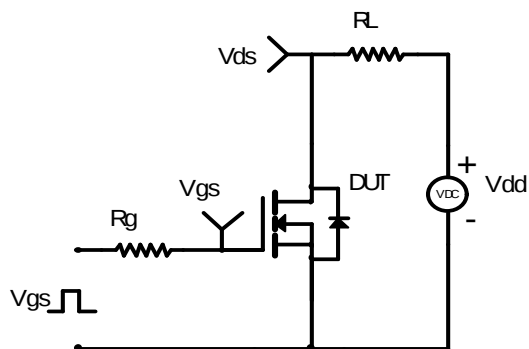


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

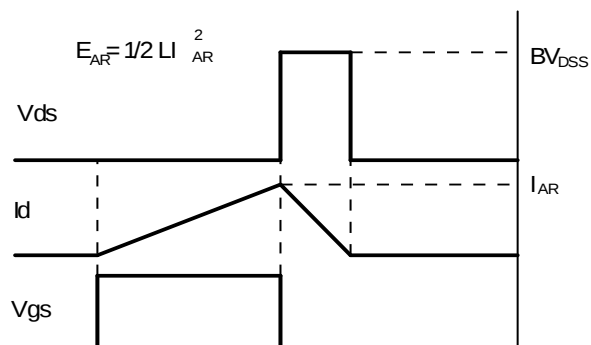
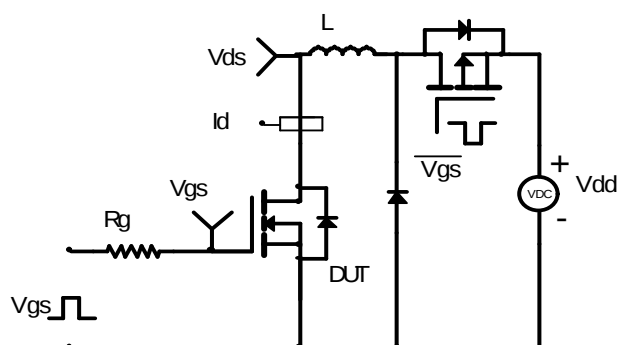
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

